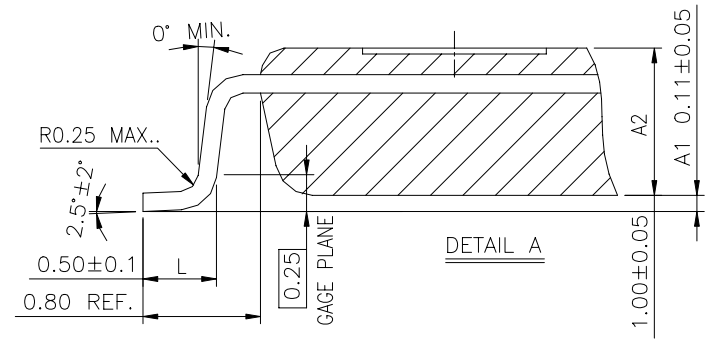
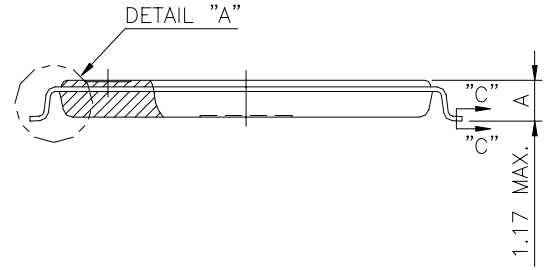
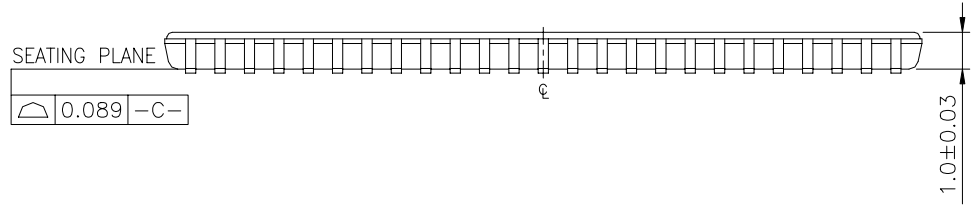


NOTES:

1. ALL DIMENSIONS ARE IN MM.
2. DIMENSION D1 AND E1 DOES NOT INCLUDE MOLD PROTRUSION.
3. COPLANARITY OF ALL LEADS SHALL BE 3.5 MILS MAX. (BEFORE TEST) UNLESS OTHERWISE SPECIFIED.
4. GENERAL PHYSICAL OUTLINE SPEC IS REFER TO TMC'S FINAL VISUAL INSPECTION SPEC UNLESS OTHERWISE SPECIFIED.
5. PLATING THICKNESS 0.200~0.800 MILS.



3			
2			
1			
REV.	DESCRIPTION OF REVISION		SIGNATURE/DATE
晶揚科技股份有限公司 Taiwan Micropaq Corporation		TSOP 50 LOC PACKAGE OUTLINE DWG.	
DWG. NO.	EOL-S0500400-001 R0		FILE S50400001
DESIGNER 劉昭真	DATE 08/16/90	MATERIAL	SCALE 5:1
CHECKER	DATE	PROCESSES	SHEET NO. 1 OF 1
APPROVED	DATE	UNIT MM	
THIRD ANGLE PROJECTION			.XXXX ±.0005 .XXX ±.0025 .XX ±.0100 .X ±.0250 ALL DIMENSIONS IN MILLIMETERS.